| L Number | Hits | | DB | Time stamp |
|----------|------------|---|-----------|--------------------|
| 1 | 17948 | tether\$2 | USPAT; | 2003/03/04 12:07 |
| | | | US-PGPUB; | |
| | | | EPO; JPO; | |
| | * | | DERWENT; | |
| | | · | IBM_TDB | |
| 2 | 1736 | tether\$2 and (chip or die) | USPAT; | 2003/03/04 12:10 |
| | | * | US-PGPUB; | |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 3 | 1 | ("5472085").PN. | USPAT | 2003/03/04 12:32 |
| 4 | 1 1 | ("6179127").PN. | USPAT | 2003/03/04 12:25 |
| 5 | 1098 | | USPAT; | 2003/03/04 12:36 |
| | | support or wafer) near (trench or aperture | US-PGPUB; | 2003, 03, 01 22.30 |
| | | or hole)) | EPO; JPO; | |
| | | or noic, | DERWENT; | · |
| : | | | | |
| 6 | 324 | ((ahip or die) game ((auhatrate or gameier | IBM_TDB | 2002/02/04 12:41 |
| О | 324 | ((chip or die) same ((substrate or carrier | USPAT; | 2003/03/04 12:41 |
| + | | or support or wafer) near (trench or | US-PGPUB; | |
| | | aperture or hole))) and((substrate or | EPO; JPO; | |
| | | carrier or support or wafer) near | DERWENT; | |
| | | (semiconductor or silicon or si or GA\$2 or | IBM_TDB | |
| | | (gallium adj arsenide))) | | |
| 7 | 0 | (((chip or die) same ((substrate or carrier | USPAT; | 2003/03/04 12:40 |
| | | or support or wafer) near (trench or | US-PGPUB; | |
| | | aperture or hole))) and((substrate or | EPO; JPO; | |
| | | carrier or support or wafer) near | DERWENT; | |
| | | (semiconductor or silicon or si or GA\$2 or | IBM TDB | |
| | * | (gallium adj arsenide)))) and tether\$2 | | |
| 8 | 0 | | USPAT; | 2003/03/04 12:40 |
| | | or support or wafer) near (trench or | US-PGPUB; | ,, |
| | | aperture or hole))) and tether\$2 | EPO; JPO; | |
| | | | DERWENT; | 1 |
| | | • | IBM TDB | |
| 9 | 1736 | tether\$2 and (chip or die) | USPAT; | 2003/03/04 12:40 |
| 1 | 1/30 | cecheryz and (chip of die) | US-PGPUB; | 2003/03/04 12:40 |
| | | | EPO; JPO; | |
| | | | | |
| | | | DERWENT; | |
| 1.0 | 1461 | /balbando / | IBM_TDB | 0000/00/04 10 41 |
| 10 | 1461 | (tether\$2 and (chip or die)) and(substrate | USPAT; | 2003/03/04 12:41 |
| | ļ | or carrier or support or wafer) | US-PGPUB; | |
| | 1 | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| 11 | 371 | (tether\$2 and (chip or die)) and ((substrate | USPAT; | 2003/03/04 12:48 |
| | | or carrier or support or wafer) with (silicon | US-PGPUB; | |
| | | or ga\$2 or si)) | EPO; JPO; | |
| 1 | | | DERWENT; | |
| | | | IBM_TDB | |
| 12 | 4387 | 206/\$.ccls. and (chip or die or | USPĀT; | 2003/03/04 12:52 |
| | | semiconductor) | US-PGPUB; | |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 13 | 114 | 206/\$.ccls. and ((chip or die) near | USPAT; | 2003/03/04 13:15 |
| į | - _ | (semiconductor or IC)) | US-PGPUB; | |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | ļ |
| 14 | 8 | 206/710.ccls. and ((chip or die) near | USPAT; | 2003/03/04 13:18 |
| | | (semiconductor or IC)) | US-PGPUB; | 2002/03/04 13:10 |
| | | (DOMEODIAGE OF TO) | | |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| 1.5 | _ | 206/2111 | IBM_TDB | 0000 (00 (00) |
| 15 | 0 | 206/7111.ccls. and ((chip or die) near | USPAT; | 2003/03/04 13:17 |
| | | (semiconductor or IC)) | US-PGPUB; | |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB | |
| | | | | |

| 16 | 0 | 206/711.ccls. and ((chip or die) | near | USPAT; | 2003/03/04 | 13:18 |
|----|-----|----------------------------------|------|-----------|------------|-------|
| | | (semiconductor or IC)) | | US-PGPUB; | | |
| | | | | EPO; JPO; | | |
| | | | | DERWENT; | | |
| | | | | IBM_TDB | | |
| 17 | 0 | 206/711.ccls. and ((chip or die) | near | USPAT; | 2003/03/04 | 13:18 |
| | | (semiconductor or IC)) | | US-PGPUB; | | |
| | | | | EPO; JPO; | | |
| | | | | DERWENT; | | |
| | | | | IBM_TDB | | |
| 18 | 568 | 257/668.ccls. and ((chip or die) | near | USPAT; | 2003/03/04 | 13:18 |
| | | (semiconductor or IC)) | | US-PGPUB; | | |
| | - | | | EPO; JPO; | | |
| | | | | DERWENT; | | |
| | | | | IBM TDB | | |